

04-01-2003

HEET

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

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the attached original documents or copy thereof.

To the Honorable Commissioner of

102405885

1. Name of conveying party(ies):

Eugene P. Marsh

3-18-03

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Internal Address: \_\_\_\_\_

Street Address: 8000 South Federal Way

City: Boise State: ID ZIP: 83716

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: March 11, 2003

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: March 11, 2003

A. Patent Application No.(s)

10392047

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mark S. Matkin

Internal Address: Wells St. John P.S.

Street Address: 601 West First Avenue, Suite 1300

City: Spokane State: WA ZIP: 99201-3828

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) ..... \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

23-0925

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark S. Matkin  
Name of Person Signing

3/18/03  
Date

Total number of pages including cover sheet, attachments, and document: 4

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

**ASSIGNMENT****PARTIES TO THE ASSIGNMENT:****INVENTOR:**

Eugene P. Marsh

**ASSIGNEE:**

Micron Technology, Inc.  
Corporation of the State of Delaware  
8000 South Federal Way  
Boise, Idaho 83716

**BACKGROUND OF THIS ASSIGNMENT:**

Inventor has conceived certain new and useful inventions disclosed in a United States patent application titled "Method of Forming a Substrate Having a Surface Comprising at Least One of Pt, Pd, Co and Au in at Least One of Elemental and Alloy Forms".

**THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt, sufficiency and adequacy of which is hereby acknowledged, INVENTOR has sold, assigned and transferred, and by these presents does hereby sell, assign and transfer to ASSIGNEE the entire right, title and interest in the above-identified inventions and application and to any reissues, renewals, divisions or continuations of the application thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.

INVENTOR further agrees to execute, at the request and expense of ASSIGNEE such other formal documents as may be required to fully convey the

interest transferred herein and will similarly execute any application papers required for the filing of any division, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTOR further assigns to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTOR agrees to execute applications relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent to ASSIGNEE as well as all other necessary papers in relation to such applications and the resulting Letters Patent to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent. INVENTOR hereby consents that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country as proof of the right of ASSIGNEE to apply for patent and other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

INVENTOR further warrants and covenants that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

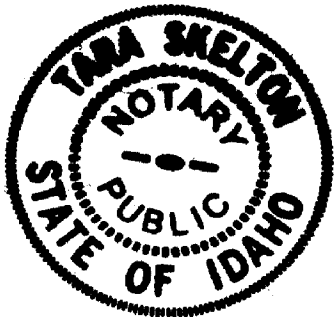
Dated: 3/11/03

Signature: *Eugene P. Marsh*  
Eugene P. Marsh

State of IDAHO )  
County of ADA ) ss.

BEFORE ME, this 11 day of MARCH, 2003, personally appeared the above-named inventor, known to me to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.

SEAL



*Tara Skelton*  
Notary or Consular Officer  
My Commission Expires: 5/18/07